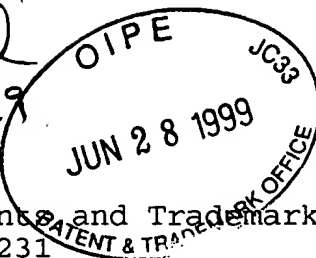


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8.31.99  
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June 23, 1999

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To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/310,256 05/12/99

S.J. Chin, S.J. Linc

A METHOD TO REDUCE PARTICLE LEVEL  
FOR DRY-ETCH

Grp. Art Unit: ~~1753~~

1746

#### INFORMATION DISCLOSURE STATEMENT

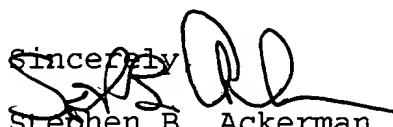
Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 5,215,619 to Cheng et al., "Magnetic Field-  
Enhanced Plasma Etch Reactor", shows a plasma reactor with a  
cleaning operation.

U.S. Patent 4,786,392 to Kruchowski et al., "Fixture for  
Cleaning a Plasma Etcher", shows a fixture for cleaning a  
plasma etcher.

Sincerely,

  
Stephen B. Ackerman,  
Reg. No. 37661